

TECHNICAL DATA SHEET

CATEGORY:

NAME:

LEAD-FREE ALLOY CASTIN^a

FEATURES

- LOWEST COST SN-AG-CU ALLOY
- LOW MELTING POINT FOR A PB-FREE ALLOY (217°C)
 SUPERIOR JOINT STRENGTH THAN SN/PB AND SN/AG
- EXCELLENT SOLDER JOINT RELIABILITY
- STRAIN RELIEVING CHARACTERISTICS
- EXCELLENT THERMAL & MECHANICAL FATIGUE RESISTANCE • LOW DROSSING & COPPER DISSOLUTION IN WAVE

217°C

LOW ALPHA EMISSIONS

DESCRIPTION

CASTIN[®] is a lead-free alloy that contains tin, silver, and copper, with the addition of a grain-refining and melting temperaturedecreasing dopant. CASTIN[®] is a virtual drop-in replacement for 63Sn/37Pb for wave soldering and hand soldering applications and has proven to perform very well in SMT applications. When used in wave soldering, CASTIN[®] produces less dross than other solder alloys, wets well, and provides excellent joint strength. In SMT applications, CASTIN[®] reduces intermetallics, produces strong solder joints, and has excellent mechanical fatigue resistance. CASTIN[®] may be used with most existing equipment, processes, coatings, and flux chemistries. The CASTIN[®] alloy is available in bar, cored and solid wire, foil, preforms, powder, and water soluble, rosin, and no-clean solder pastes. CASTIN[®] solder products pass all applicable IPC specifications, including IPC-J-STD-006.

PHYSICAL PROPERTIES

Sn63/Pb37	CASTIN®
4.92	5.73
4.38	4.86
4.87	7.42
3.99	4.26
4.52	4.33
7.17	8.54
	Sn63/Pb37 4.92 4.38 4.87 3.99 4.52 7.17

CASTIN[®] MELTING POINT

 ALLOY COMPOSITION in Percent

 Ag: 2.5 ± 0.25
 Al: = 0.001
 As: = 0.05
 Au: = 0.05
 Bi: = 0.03

 Cd: = 0.001
 Cu: 0.75 ± 0.25
 Fe: = 0.08
 In: = 0.01
 Ni: = 0.005

 Sb: 0.50 ± 0.25
 Sn: Balance
 Zn: = 0.005

HANDLING

Refer to the specific Material Safety Data Sheet and the handling section of the individual Technical Data Sheets for the chemistry type of CASTIN[®] solder paste being used.

FLUX COMPATIBILITY

CASTIN[®] is compatible with all major electronic grade fluxes on the market today, and is available in paste and wire form in noclean, water soluble and rosin chemistries.

CLEANING

Refer to the liquid flux manufacturer's data sheet for specific cleaning information, or refer to the cleaning section of the individual AIM solder paste technical data sheets for the recommended cleaning information.

TEMPERATURE REQUIREMENTS

APPLICATION	RECOMMENDED TEMPERATURE
REFLOW SOLDERING	PEAK TEMPERATURE 235° - 245°C (455° - 473°F)
WAVE SOLDERING	POT TEMPERATURE OF 260°C (500°F)
HAND SOLDERING	TIP TEMPERATURE OF 370° - 425°C (700° - 800°F)

SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

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Americas +1-401-463-5605 • Europe +44-1737-222-258 • Asia-Pacific +852-2649-7183 • info@aimsolder.com • www.aimsolder.com